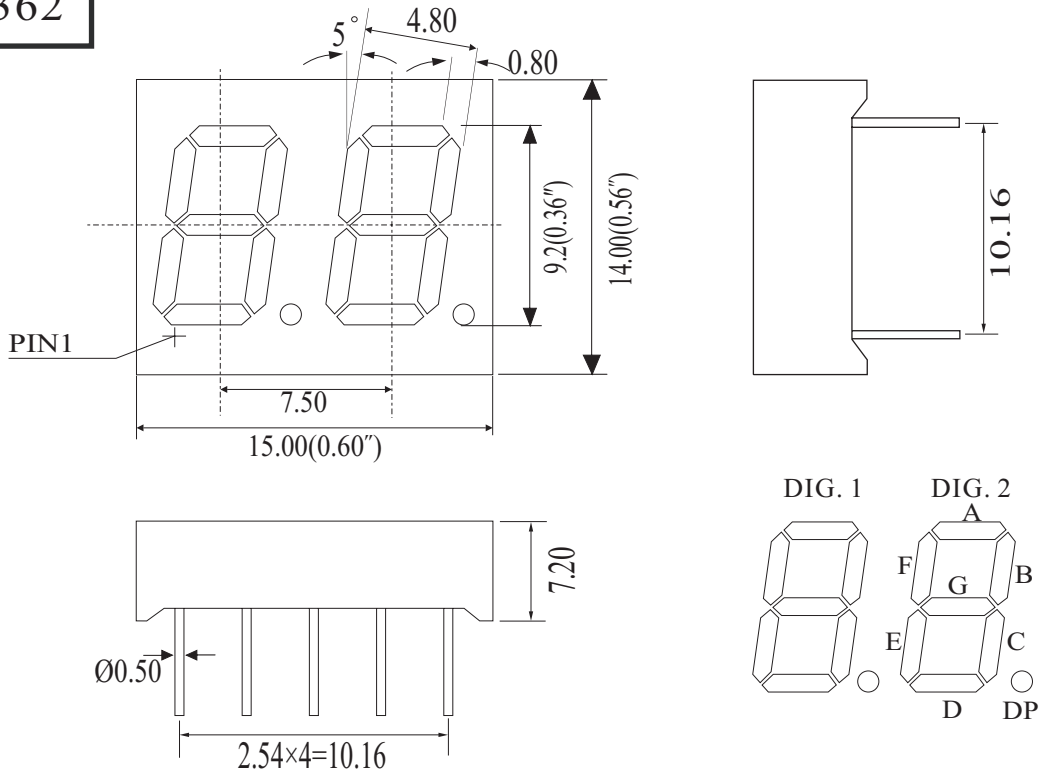


Part Number System for Displays

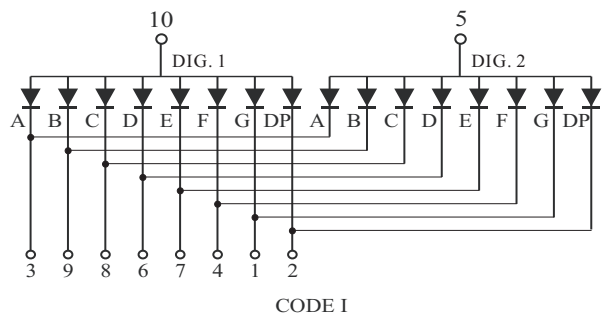
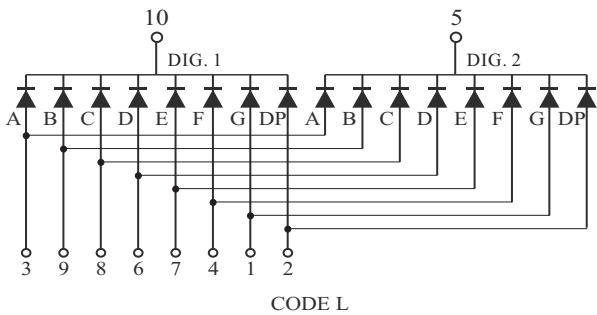
PACKAGE DIMENSION

E20362



UNIT: MM(INCH) TOLERANCE: $\pm 0.25(0.01)$ "

INTERNAL CIRCUIT DIAGRAM



CODE K2

Chip Material: GaP / GaP Yellow Green LED Chip



ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

PARAMETER	SYMBOL	MAXIMUM RATING	UNIT
Power Dissipation	P _D	65	mW
Peak Forward Current (1/10 Duty Cycle, 0.1 Ms Pulse Width)	I _{PEAK}	140	mA
DC Forward Current	I _F	25	mA
Reverse Voltage	V _R	5	V
Operating Temperature Range	T _A	-40°C to +85°C	
Storage Temperature Range	T _{STG}	-40°C to +85°C	
Solder temperature 1/16 inch below seating plane for 3 seconds at 260°C			

ELECTRICAL OPTICAL CHARACTER AND CURVES (Ta = 25°C)

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	LOCATION	TEST CONDITION
Forward Voltage	V _F	-	2.30	2.60	V	Per Chip	I _F = 20mA
Luminous Intensity	I _v	11.0	12.0	13.0	mcd	Per Chip	I _F = 20mA
Peak Emission Wavelength	λ _p	-	568	-	nm	Per Chip	I _F = 20mA
Dominant Emission Wavelength	λ _d	567	572	577	nm	Per Chip	I _F = 20mA
Spectral Line Half-Width	Δλ _{1/2}	-	30	-	nm	Per Chip	I _F = 20mA
Capacitance	C	-	15	-	pF	Per Chip	V _F = 0V; f = 1MHz
Reverse Current	I _R	-	-	10	uA	Per Chip	V _R = 5V

Note:

1. Luminous intensity tolerance is ±10%;
2. Dominant Emission Wavelength tolerance is ±5%.

CODE K2

■ Typical Electro-Optical Characteristic Curve:

FIG. 1 Forward Current Vs. Forward Voltage

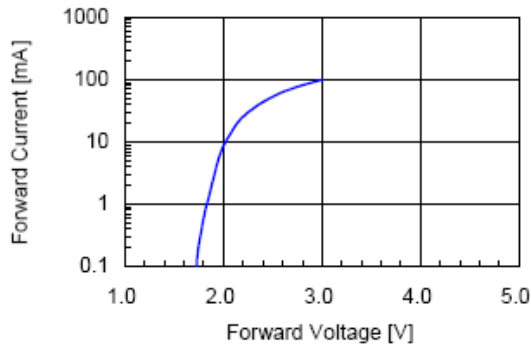


FIG. 2 Relative Intensity Vs. Forward Current

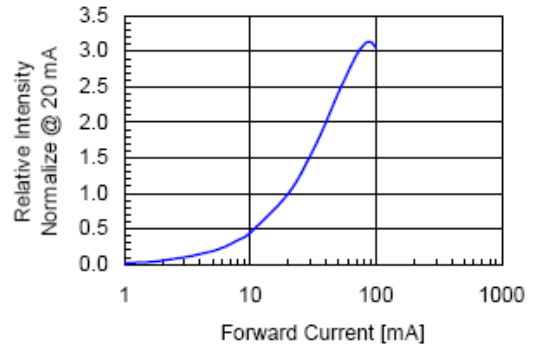


FIG. 3 Forward Voltage Vs. Temperature

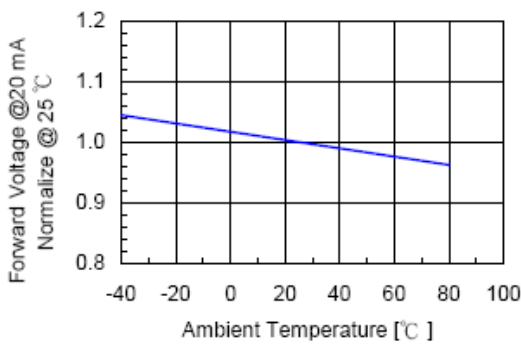


FIG. 4 Relative Intensity Vs. Temperature

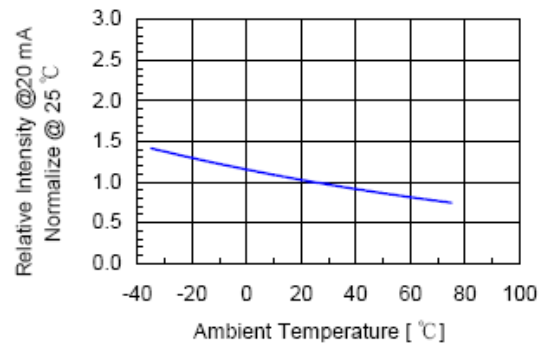


FIG. 5 Relative Intensity Vs. Wavelength

